

HUGO ONGHAI

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EDUCATION

Cornell Tech, Cornell University

New York, New York

M. Eng. in Electrical and Computer Engineering

Expected June 2026

- GPA: 4.0/4.0
- Recipient of Cornell Tech Merit Scholarship and Admission Office Student Ambassador

University of California, Los Angeles (UCLA)

Los Angeles, California

B.S. in Materials Engineering with specializations in Electronic Materials and Math of Computation

June 2025

- Cumulative GPA: 3.975/4.0; summa cum laude; 5x Dean's Honor List
- Recipient of Chin Family Endowed Engineering Scholarship (2024), Knapp Scholarship for Ceramics Studies (2023)
- Relevant Coursework: Machine Learning for MSE, Computer Methods of MSE, Honors Proof-Based Linear Algebra

RESEARCH

Ab Initio Simulations Lab @ UCLA

Los Angeles, California

IBM Research Scholar

September 2023 – Present

- Awarded competitive scholarship from IBM to conduct undergraduate research, through the Semiconductor Research Corporation Undergraduate Research Program
- Writing in-house scripts for MSPARC, a real space density functional theory package for MATLAB, to better analyze band structures of exotic electronic materials

Institute for Biological Information Processing (Bioelectronics)

Forschungszentrum Jülich, Germany

DAAD RISE Intern

June 2024 – September 2024

- Awarded competitive scholarship to research at Forschungszentrum Jülich, one of Europe's largest research centers
- Demonstrated a greatly improved accelerated aging tests process and setup on 3D-printed, flexible neural implants
- Performed electrochemical impedance spectroscopy, charge injection capacity testing, and data analysis with galvani, Matplotlib, seaborn, NumPy, and pandas

Center for Thermal Spray Research at Stony Brook University

Stony Brook, New York

Research Intern

July 2022 – August 2022

- Studied the relationship of stiffness and spray distance and changes in porosity via impulse excitation
- Designed MATLAB script to run point tracking algorithm on spray-coated samples undergoing three-point bend testing to visualize crack propagation and measure strain

Nagan Research Lab

Stony Brook, New York

Simons Fellowship Research Intern

June 2021 – August 2021

- Used torsion bond-angle analysis technique to characterize molecular dynamics simulations
- Gained valuable experience with AMBER simulation, Jmol visualization, and remote Linux systems

Garcia Center for Polymers at Engineered Interfaces

Stony Brook, New York

Garcia Research Scholars Summer Intern

June 2020 – September 2020

- Analyzed AFM and CV data of gold thin-films on silicon wafers as potentiometric biosensors
- Awarded "Most Outstanding Exhibit in Material Science" distinction by American Materials Society

WORK EXPERIENCE

Materials Project

Lawrence Berkeley National Lab, California

Materials Informatics Database Intern

June 2025 – August 2025

- Used Python and MongoDB to manage the submission and documentation of DOI numbers as released by the U.S. Department of Energy's Office of Science and Technology Information.

Cedar Hill Cemetery

Port Jefferson, New York

Gravedigger and Grounds Laborer

August 2023 – June 2024

- Performed over 20 funeral and burial services in first 2 months
- Learned to help people during their hardest times in life and in moments of great emotional distress

LEADERSHIP & INVOLVEMENT

Materials Research Society at UCLA

Los Angeles, California

Historian and Web-Dev Team Member

May 2023 – June 2024

- Serve as sole editor, writer, and designer for quarterly alumni newsletters and professor interview series
- Using WordPress to design a new and streamlined organization website
- Established new LinkedIn group, so far connecting 100 alumni, students, and faculty in its first year

UCLA Women's and Men's Volleyball Production Team

Los Angeles, California

Student DJ/Audio Engineer

September 2023 – April 2024

- Curate, play, and remix music for UCLA D1 Women's Volleyball Home Games
- Gained experience with stadium sound systems, audio engineering, and fast team coordination